

Title (en)  
INDUCTIVE COMPONENT AND USE OF SAID COMPONENT

Title (de)  
INDUKTIVES BAUELEMENT UND VERWENDUNG DES BAUELEMENTS

Title (fr)  
COMPOSANT INDUCTIF ET UTILISATION DE CELUI-CI

Publication  
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Application  
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Abstract (en)  
[origin: WO2004017338A1] The invention relates to an inductive component (1), for the formation of a magnetic circuit, comprising at least one wire winding (3) and at least one core (4) with a ferromagnetic core material. Said core comprises a gap (7, 8) and at least one further gap (8, 7) to interrupt the magnetic circuit. The inductive component is characterised in that the gaps each have a gap width of at least 1.0mm. The core comprises two pieces, for example, which are arranged opposed to each other across the gaps (7, 8) and separated from each other by the gap width. The component is advantageously symmetrical with an essentially equal gap width for the gaps. A miniaturised inductive component is possible by the use of a wire winding made from high frequency braided wire and core material capable of accepting high frequencies, which has a high Q-factor even on a high power throughput and thus low electrical losses. In order to increase the Q-factor, the inductive component also has a cooling device for cooling the wire winding. The device is thus provided with a composite material with a thermally-conducting filler. The inductive component is used in a so-called electronic ballast (EVG) in the field of illumination.

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